ABSTRACT

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING SAME

A semiconductor device has (a) a semiconductor component; (b) a circuit substrate; (c) a base material which is placed between the semiconductor component and the circuit substrate; and (d) a conductive paste, which is filled into a hole formed in the base material, for electrically connecting between a terminal electrode of the semiconductor component and an internal connection electrode of the circuit substrate.

FIGURE 1e

This Sheet Has Been Replaced

